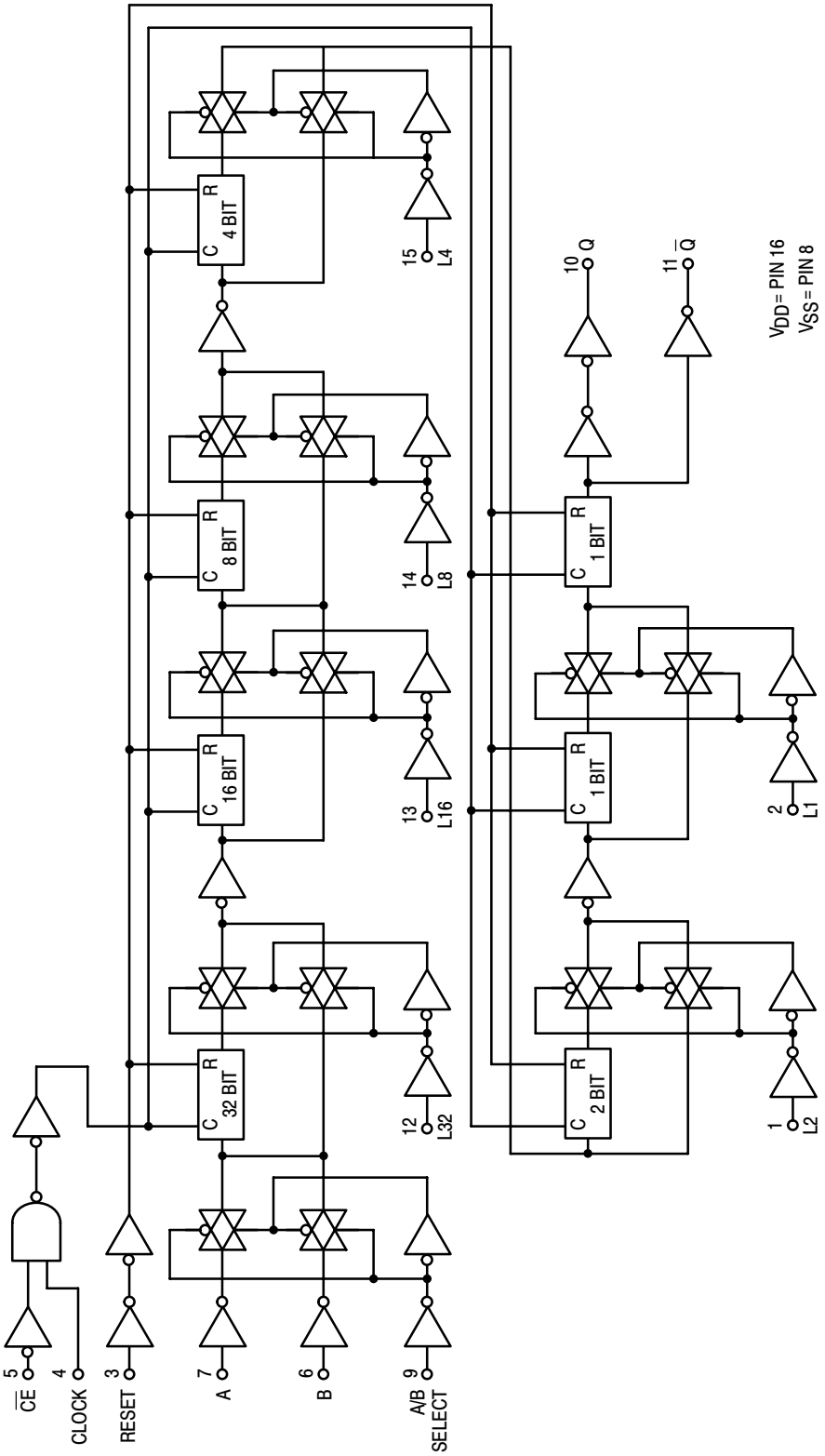


Figure 1. Logic Diagram

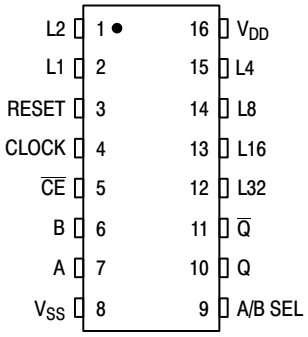


Figure 2. Pin Assignment

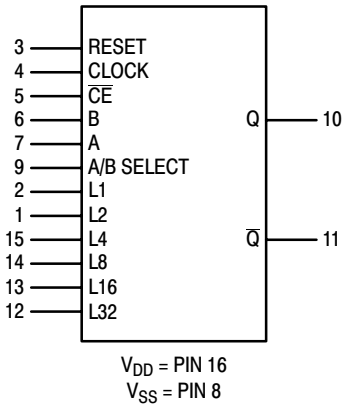


Figure 3. Block Diagram

TRUTH TABLE

Inputs				Output
Rst	**A/B**	**Clock**	**$\overline{CE}$**	**Q**
0	0	⎍	0	B
0	1	⎍	0	A
0	0	1	⎏	B
0	1	1	⎏	A
1	X	X	X	0

Q is the output of the first selected shift register stage.
X = Don't Care

LENGTH SELECT TRUTH TABLE

L32	L16	L8	L4	L2	L1	Register Length
0	0	0	0	0	0	1 Bit
0	0	0	0	0	1	2 Bits
0	0	0	0	1	0	3 Bits
0	0	0	0	1	1	4 Bits
0	0	0	1	0	0	5 Bits
0	0	0	1	0	1	6 Bits
•	•	•	•	•	•	•
•	•	•	•	•	•	•
•	•	•	•	•	•	•
1	0	0	0	0	0	33 Bits
1	0	0	0	0	1	34 Bits
•	•	•	•	•	•	•
•	•	•	•	•	•	•
•	•	•	•	•	•	•
1	1	1	1	0	0	61 Bits
1	1	1	1	0	1	62 Bits
1	1	1	1	1	0	63 Bits
1	1	1	1	1	1	64 Bits

NOTE: Length equals the sum of the binary length control subscripts plus one.

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Symbol	Characteristic	V_{DD} Vdc	− 55°C Min	− 55°C Max	25°C Min	25°C Typ (Note 3)	25°C Max	125°C Min	125°C Max	Unit
V_{OL}	Output Voltage “0” Level V_{in} = V_{DD} or 0	5.0 10 15	− − −	0.05 0.05 0.05	− − −	0 0 0	0.05 0.05 0.05	− − −	0.05 0.05 0.05	Vdc
V_{OH}	“1” Level V_{in} = 0 or V_{DD}	5.0 10 15	4.95 9.95 14.95	− − −	4.95 9.95 14.95	5.0 10 15	− − −	4.95 9.95 14.95	− − −	Vdc
V_{IL}	Input Voltage “0” Level (V_O = 4.5 or 0.5 Vdc) (V_O = 9.0 or 1.0 Vdc) (V_O = 13.5 or 1.5 Vdc)	 5.0 10 15	 − − −	 1.5 3.0 4.0	 − − −	 2.25 4.50 6.75	 1.5 3.0 4.0	 − − −	 1.5 3.0 4.0	Vdc
V_{IH}	“1” Level (V_O = 0.5 or 4.5 Vdc) (V_O = 1.0 or 9.0 Vdc) (V_O = 1.5 or 13.5 Vdc)	 5.0 10 15	 3.5 7.0 11	 − − −	 3.5 7.0 11	 2.75 5.50 8.25	 − − −	 3.5 7.0 11	 − − −	Vdc
I_{OH}	Output Drive Current (V_{OH} = 2.5 Vdc) Source (V_{OH} = 4.6 Vdc) (V_{OH} = 9.5 Vdc) (V_{OH} = 13.5 Vdc)	 5.0 5.0 10 15	 –3.0 –0.64 –1.6 –4.2	 − − − −	 –2.4 –0.51 –1.3 –3.4	 –4.2 –0.88 –2.25 –8.8	 − − − −	 –1.7 –0.36 –0.9 –2.4	 − − − −	mAdc
I_{OL}	(V_{OL} = 0.4 Vdc) Sink (V_{OL} = 0.5 Vdc) (V_{OL} = 1.5 Vdc)	5.0 10 15	0.64 1.6 4.2	− − −	0.51 1.3 3.4	0.88 2.25 8.8	− − −	0.36 0.9 2.4	− − −	
I_{in}	Input Current	15	−	±0.1	−	±0.00001	±0.1	−	±1.0	μAdc
C_{in}	Input Capacitance (V_{in} = 0)	−	−	−	−	5.0	7.5	−	−	pF
I_{DD}	Quiescent Current (Per Package)	5.0 10 15	− − −	5.0 10 20	− − −	0.010 0.020 0.030	5.0 10 20	− − −	150 300 600	μAdc
I_T	Total Supply Current (Notes 4, 5) (Dynamic plus Quiescent, Per Package) (C_L = 50 pF on all outputs, all buffers switching)	5.0 10 15	I_T = (1.75 μA/kHz) f + I_{DD} I_T = (3.50 μA/kHz) f + I_{DD} I_T = (5.25 μA/kHz) f + I_{DD}							μAdc

3. Data labelled “Typ” is not to be used for design purposes but is intended as an indication of the IC’s potential performance.
4. The formulas given are for the typical characteristics only at 25°C.
5. To calculate total supply current at loads other than 50 pF: $I_T(C_L) = I_T(50\ pF) + (C_L - 50)$ Vfk where: I_T is in μA (per package), C_L in pF, V = ($V_{DD} - V_{SS}$) in volts, f in kHz is input frequency, and k = 0.001.

SWITCHING CHARACTERISTICS (Note 6) (C_L = 50 pF, T_A = 25°C)

Symbol	Characteristic	V_{DD}	Min	Typ (Note 7)	Max	Unit
t_{TLH}, t_{THL}	Rise and Fall Time, Q or $\overline{Q}$ Output					ns
	t_{TLH}, t_{THL} = (1.5 ns/pF) C_L + 25 ns	5	–	100	200	
	t_{TLH}, t_{THL} = (0.75 ns/pF) C_L + 12.5 ns	10	–	50	100	
	t_{TLH}, t_{THL} = (0.55 ns/pF) C_L + 9.5 ns	15	–	40	80	
t_{PLH}, t_{PHL}	Propagation Delay, Clock or $\overline{CE}$ to Q or $\overline{Q}$					ns
	t_{PLH}, t_{PHL} = (1.7 ns/pF) C_L + 215 ns	5	–	300	600	
	t_{PLH}, t_{PHL} = (0.66 ns/pF) C_L + 97 ns	10	–	130	260	
	t_{PLH}, t_{PHL} = (0.5 ns/pF) C_L + 65 ns	15	–	90	180	
t_{PLH}, t_{PHL}	Propagation Delay, Reset to Q or $\overline{Q}$					ns
	t_{PLH}, t_{PHL} = (1.7 ns/pF) C_L + 215 ns	5	–	300	600	
	t_{PLH}, t_{PHL} = (0.66 ns/pF) C_L + 97 ns	10	–	130	260	
	t_{PLH}, t_{PHL} = (0.5 ns/pF) C_L + 70 ns	15	–	95	190	
$t_{WH(cl)}$	Pulse Width, Clock	5	200	95	–	ns
		10	100	45	–	
		15	75	35	–	
$t_{WH(rst)}$	Pulse Width, Reset	5	300	150	–	ns
		10	140	70	–	
		15	100	50	–	
f_{cl}	Clock Frequency (50% Duty Cycle)	5	–	3.0	1.7	MHz
		10	–	7.5	5.0	
		15	–	13.0	6.7	
t_{su}	Setup Time, A or B to Clock or $\overline{CE}$					ns
	Worst case condition: L1 = L2 = L4 = L8 =	5	700	350	–	
	L16 = L32 = V_{SS} (Register Length = 1)	10	290	130	–	
		15	145	85	–	
	Best case condition: L32 = V_{DD}, L1 through L16 =	5	400	45	–	
	Don't Care (Any register length from 33 to 64)	10	165	5	–	
		15	60	0	–	
t_h	Hold Time, Clock or $\overline{CE}$ to A or B					ns
	Best case condition: L1 = L2 = L4 = L8 = L16 =	5	200	–150	–	
	L32 = V_{SS} (Register Length = 1)	10	100	–60	–	
		15	10	–50	–	
	Worst case condition: L32 = V_{DD}, L1 through L16 =	5	400	50	–	
	Don't Care (Any register length from 33 to 64)	10	185	25	–	
		15	85	22	–	
t_r, t_f	Rise and Fall Time, Clock	5	No Limit			–
		10				
		15				
t_r, t_f	Rise and Fall Time, Reset or $\overline{CE}$	5	–	–	15	μs
		10	–	–	5	
		15	–	–	4	
t_{rem}	Removal Time, Reset to Clock or $\overline{CE}$	5	160	80	–	ns
		10	80	40	–	
		15	70	35	–	

6. The formulas given are for the typical characteristics only at 25°C.
7. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

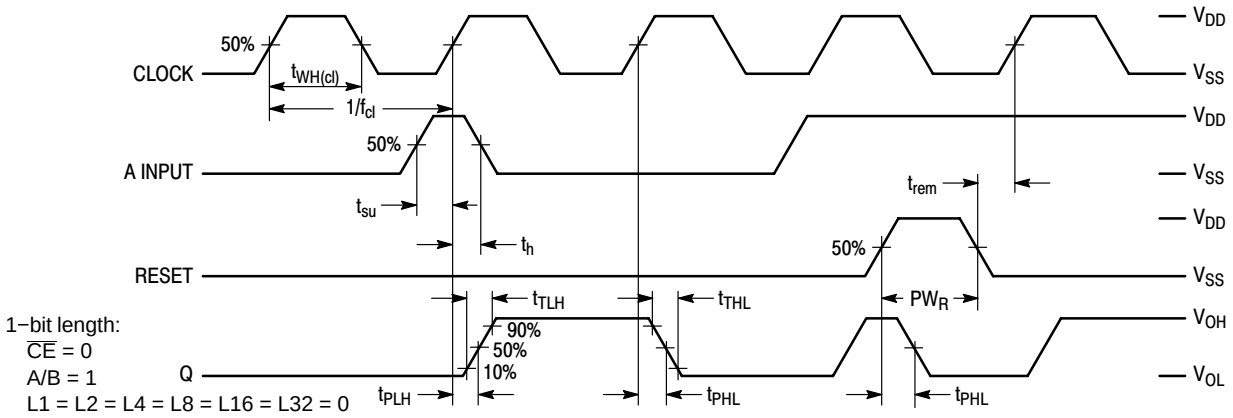


Figure 4. Timing Diagram

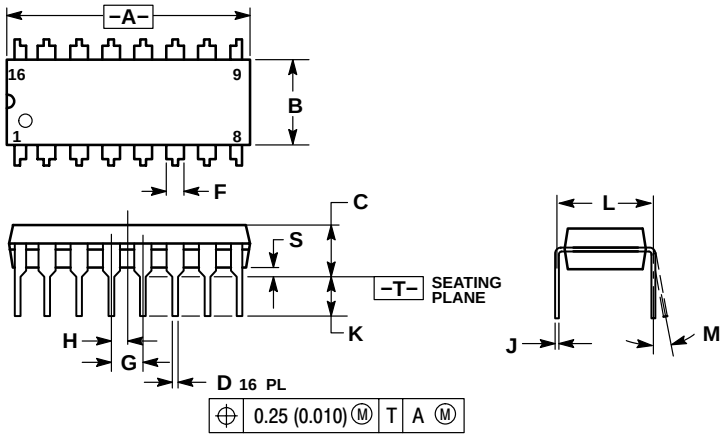
ORDERING INFORMATION

Device	Package	Shipping†
MC14557BF	SOEIAJ−16 (Pb−Free)	50 Units / Rail
MC14557BCP	PDIP−16	500 Units / Rail
MC14557BFEL	SOEIAJ−16 (Pb−Free)	2000 / Tape & Reel
MC14557BDWR2	SO−16 (WB)	1000 / Tape & Reel
MC14557BCPG	PDIP−16 (Pb−Free)	500 Units / Rail
MC14557BDW	SO−16 (WB)	47 Units / Rail

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

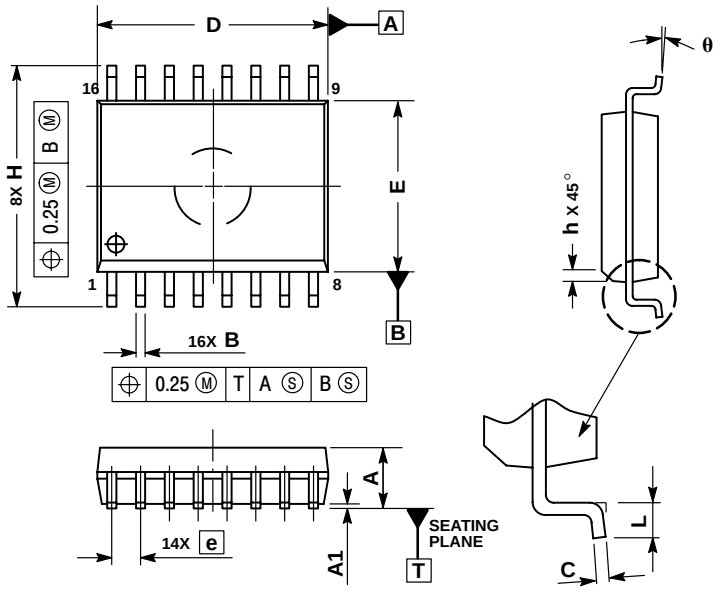
PDIP−16
P SUFFIX
CASE 648−08
ISSUE T



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0 °	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

SO−16 WB
DW SUFFIX
CASE 751G−03
ISSUE C

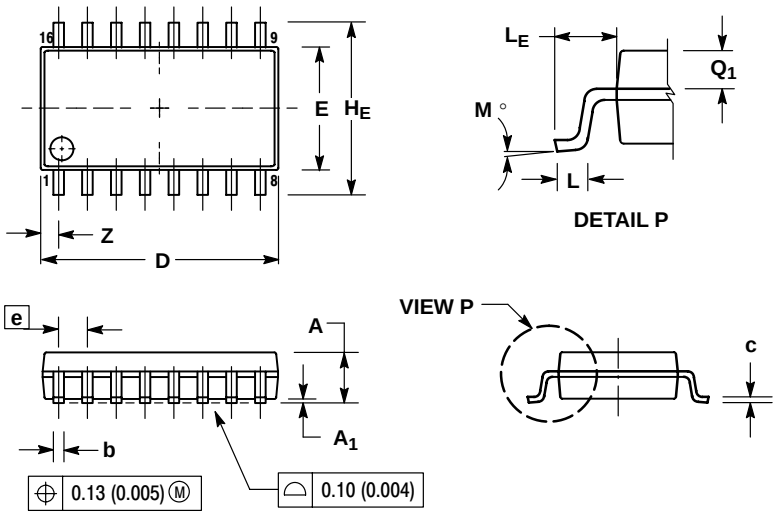


NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INLCUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS	
DIM	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
B	0.35	0.49
C	0.23	0.32
D	10.15	10.45
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
q	0 °	7 °

PACKAGE DIMENSIONS

SOEIAJ−16
F SUFFIX
CASE 966−01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A_1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q_1	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

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